QUALITY AND RELIABILITY ENGINEERING INTERNATIONAL
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CUMULATIVE CONTENTS, VOLUMES 1–10

VOLUME 1, ISSUE Nos 1–4

Issue No. 1, January–March 1985

Editorial 1

Methods and Limitations of Assessing the Hermeticity of Semiconductor Component Encapsulations: R. P. Merrett 3

Activation Energies and the Arrhenius Equation: F. Jensen 13

Effectiveness of Formal Reliability Programmes: P. D. T. O'Connor 19

Graphical Weibull Analysis of Repairable Systems: G. Härtler 23

Quantitative Demonstration and Cost Considerations of a Software Fault Removal Methodology: M. Lipow 27

Exploring Reliability Data: A. Bendell and L. A. Walls 37

Weibull Probability Paper used on Highly Stressed Bimodal Components: A. Drapella 53

NEWS ITEMS 57

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 58

Call for Papers and Advance Information 60

BOOK REVIEWS 62

Report Reviews 64

RESEARCH AND METHODS 66

INDEPENDENT TEST HOUSES 66

Issue No. 2, April–June 1985

Editorial 69

Automated Quality Management Systems in the Electronics Factory of the Future: B. Davis 71

The Rationale of Reliability Prediction: L. N. Harris 77

Research into the Use of Statistical Quality Control in British Manufacturing Industry—Part I: R. F. Followell and J. S. Oakland 85

A Management View of Software Reliability: A. Wingrove 93

Quantitative Effects of Electrical and Vibrational Stresses on Reliability: K. L. Wong 99

Reliability of Plastic-encapsulated Integrated Circuits in Moisture Environments: L. Gallace and M. Rosenfield 105

Index or abstracted by Cambridge Scientific Abstracts, Engineering Index, INSPEC, Materials Information, Operations Research/Management Science, Research Alert, SciSearch, Quality Control & Applied Statistics and VINITI—U.S.S.R. Academy of Science

Electrostatic Discharge: Mechanisms, Protection Techniques and Effects on Integrated Circuit Reliability: L. R. Avery 119
Burn-in Models and TTT-transforms: B. Bergman and B. Klefsjö 125
NEWS ITEMS 131
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 134
BOOK REVIEWS 138
INDEPENDENT TEST HOUSES 142

Issue No. 3, July–September 1985

Editorial 143
SHORT COMMUNICATION
A Message to Quality and Reliability Professionals: D. A. Stuart 145
Reliability in Communications Satellites: V. J. Mancino and W. J. Slusark, Jr 147
Estimation of Weibull Reliability from Few Life Tests: P. Erto and M. Guida 161
A Failure Analysis Methodology for Revealing ESD Damage to Integrated Circuits: R. G. Taylor, J. Woodhouse and P. R. Feasey 165
The Reliability Engineer Looks at Stress Screening: W. Tustin 173
The Use of Models in Reliability: L. N. Harris 181
Reliability Analysis of Fault Tolerance Memory Arrays: J. A. Nachlas 191
Traffic Signal Equipment Procurement Based on Cost of Ownership and Community Cost: H. S. Blanks 195
NEWS ITEMS 209
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 210
Courses in Quality and Reliability 212
BOOK REVIEWS 214

Issue No. 4, October–December 1985

Editorial 217
VLSI Yield Management and Prediction: A. V. Ferris-Prabhu 219
Quality Control Information Systems: D. Prior 227
Reliability Analysis Techniques for Mechanical Systems: N. Bernstein 235
Mechanical Reliability, How Do We Advance?: V. Loll 249
How Pulsed Operation Affects Aluminium Bond Wires: G. Fredriksson 257
NEWS ITEMS 263
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 264
Call for Papers and Advance Information 267
INDEPENDENT TEST HOUSES 267
BOOK REVIEWS 269
Author Index 272
Key Word Index 272

VOLUME 2, ISSUE Nos 1–4

Issue No. 1, January–March 1986

Editorial 1
A General Model for Age Acceleration During Thermal Cycling: J. A. Nachlas 3
Mechanical Reliability by Design: A. D. S. Carter 7
Forecasting Reliability Growth: D. K. Lloyd 19
In Defence of Numerical Techniques: G. E. Benz 25
Stress Test Development on a Processor System: K. Venn 33
Reliability Indicators: F. Jensen and J. Møltoft 39
Proportional Hazards Modelling in Reliability Analysis—An Application of Brake Discs on High Speed Trains: A. Bendell, M. Walley, D. W. Wightman and L. M. Wood 45
Random Failures Not Allowed Here—The US Roland Case History: W. D. Currie and E. G. Stauss 53
NEWS DIGEST 57
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 60
RESEARCH AND METHODS 64
BOOK REVIEWS 65
Report Reviews 67

Issue No. 2, April–June 1986

Editorial 69
A Review of the 'Taguchi Methods' for Off-line Quality Control: L. Basso, A. Winterbottom and H.P. Wynn 71
Factors Involved in Electrically Testing VLSI Circuits: E. R. Hnatek 81
A New Approach to Reliability Prediction is Needed: R. A. Florescu 101
Electrostatic Pulse Breakdown in NMOS Devices: E. A. Amerasekera and D. S. Campbell 107
The Robustness of Markov Reliability Models: J. F. Edgar and T. Bendell 117
Quality and Reliability Assurance for Electronic Systems—Actions and Results: U. Ender 127
NEWS DIGEST 131
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 132
Courses in Quality and Reliability 135
BOOK REVIEWS 137
Report Review 139

Issue No. 3, July–September 1986

Editorial 141
Use of Liquid-crystal Thermography for Defect Location on Semiconductor Devices: F. Beck 143
Calculation of Optimum Proof Test Intervals for Maximum Availability: G. R. Duke 153
The Test Needs of Applications-specific Integrated Circuits: C. Davison 159

Cathode Ray Tube Bleed Resistor Reliability—A Case Study: P. Hale, I. Mactaggart and M. Shaw 165
Production Reliability in Flexible Manufacturing System: K. Khodabandehloo and R. S. Sayles 171
Optimum Replacement of Deteriorating and Inadequate Equipment: H. S. Blanks and M. J. Tordon 183
Fatigue Analysis for Crack Initiation: C. C. S. Yen 199
NEWS DIGEST 209
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 210
RESEARCH AND METHODS 213
Reports 214
BOOK REVIEWS 216
Report Review 218

Issue No. 4, October–December 1986

Editorial 219
Economic Models and Process Quality Control: D. C. Montgomery and R. H. Storer 221
Surface Mount Digital Package Reliability: W. J. Roesch 229
Simplified Markov Techniques for some Stand-by Redundant Systems: R. Hamilton and I. Bazovsky, Sr 233
Goodness of Fit of Small Samples to the Weibull Distribution: R. D. Leitch 241
Failure Analysis on Bipolar Integrated Circuits Attributes Damage to Electrostatic Discharge: G. N. Wills 247
Semiconductor Device Burn-in, Is there a Future?: R. Parsons 255
Acceleration and Time to Fail: P. W. Hale 259
Reliability of a Dynamic Random Access Memory (DRAM): P. W. Hale 263
NEWS DIGEST 267
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 268
Courses in Quality and Reliability 270
BOOK REVIEWS 273
Report Review 275
Author Index 276
Key Word Index 276

VOLUME 3, ISSUE Nos 1–4

Issue No. 1, January–March 1987

Editorial 1
Integrated Circuits for Submarine Communication Systems, Their Design and Development: A. J. Tew 3
Using Statistical Control Charts for Software Quality Control: J. S. Gardiner and D. C. Montgomery 15

Functional Screens for Electronic Reliability: W. A. Ganter 21

R & M Implications of Leadless Chip Carriers (LCCs): H. E. Fox 25

Research into the Use of Statistical Quality Control in British Manufacturing Industry—Part II: R. F. Followell and J. S. Oakland 33

Application of a Multi-Model Approach to Estimating Residual Software Faults and Time Between Failures: J. B. Bowen 41

A Note on the Average Run Length of Cumulative Sum Control Charts for Count Data: J. S. Gardiner, D. J. Friedman and D. C. Montgomery 53

NEWS DIGEST 57

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 60

RESEARCH AND METHODS 64

BOOK REVIEWS 69

Report Review 73

Issue No. 2, April–June 1987

Editorial 75

Letter to the Editor 76

Applications of the Weibull Proportional Hazards Model to Aircraft and Marine Engine Failure Data: A. K. S. Jardine, P. M. Anderson and D. S. Mann 77

Monte Carlo Methods in Reliability Engineering: A. Goldfeld and A. Dubi 83

The Influence of Climatic Conditions on the Reliability of Electronic Components in Telephone Exchanges: A. Lelievre and R. Goarin 93

Reliability Characterization of a 3-μm CMOS/SOS Process: M. P. Dugan 99

Quality Assurance Technologies for VLSI Manufacturing: H. J. Kohoutek 107

NEWS DIGEST 127

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 130

COURSES IN QUALITY AND RELIABILITY 133

RESEARCH AND METHODS 136

BOOK REVIEWS 141

REPORT REVIEWS 143

Issue No. 3, July–September 1987

Editorial 145

The Deacon's Masterpiece: Oliver Wendell Holmes 147

Load-strength Modelling of Mechanics and Electronics: V. Loll 149

Development of Stress Screens: G. K. Hobbs 157

Considerations in the Use of Optimal Preventive Maintenance Policies: N. A. Zaino, Jr. 163

Quality Assurance Education and Training in the U.K.: J. S. Oakland and R. Grayson 169

Purple Plague: Eliminated or Just Forgotten?: P. K. Footner, B. P. Richards and R. B. Yates 177

A Rapid Technique for Assessing the Moisture Ingress Susceptibility of Plastic–encapsulated Integrated Circuits: E. J. Chwastek and R. N. Shaw 185

Influence of Quality Manufacture on Electronic Equipment and System Reliability: U. Ender and W. Gerling 195

NEWS DIGEST 203

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 206

BOOK REVIEWS 210

Issue No. 4, October–December 1987

Editorial 215

SHORT COMMUNICATION

The Reliability Growth Myth or Mess: K. L. Wong 217

Estimation and Test for the Parameters of the Arrhenius Model: G. Härtler 219

Off-line Quality Control and Ill-designed Data: N. Logothetis 227

Component Reliability Assessment and Assurance Using a New Step-stress Test: S. M. Aagesen and J. L. Stevenson 239

The Organization of a Study of the Field Failure of Electronic Components: D. S. Campbell, J. A. Hayes and D. R. Hetherington 251

Recognizing the Optimum Burn-in Period: M. Shaw 259

Some Factors to Consider in Developing a Quality-related Feedback System: J. C. Staveley and B. G. Dale 265

Height-keeping Reliability of Aircraft at High Altitude: W. P. Cannell 273

NEWS DIGEST 281

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 284

Courses in Quality and Reliability 287

BOOK REVIEWS 290

Author Index 293

Key Word Index 293

VOLUME 4, ISSUE Nos 1–4

Issue No. 1, January–March 1988

Editorial 1

Letter to the Editor 2

SHORT COMMUNICATIONS

Reliability Prediction using Alternative Methods 3

Quality in Design: W. A. Ganter 4

A Mechanical Decapsulation Technique for Epoxide-packaged Semiconductor Components: E. J. Chwastek and I. A. Holland 7

Causes and Effects of Spacecraft Failures: M. Hecht and E. Fiorentino 11

Parameter Estimation for the Two-parameter Weibull Distribution using Sample Statistics and the Jack-knife: A. F. Bissell 21

Early Life Failures: B. A. Unger 27

The Inherent Unreliability of Reliability Data: C. Mallagh 35

Fatigue Reliability Assessment of Offshore Structures: J. C. P. Kam 41

The Role of Data Transformation in Taguchi Analysis: N. Logothetis 49

A Managerial Tool for Process Capability Analysis: D. S. Holmes and A. E. Mergen 63

Accounting for Maintenance in a Computer Memory Reliability Prediction Model: J. E. Miller, H. Hecht and S. Morris 67

NEWS DIGEST 73

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 76

Courses in Quality and Reliability 79

BOOK REVIEWS 81

Issue No. 2, April–June 1988
Special Issue on Taguchi Methods
Guest Editor: Norman Harris

Editorial 85

Parameter Tolerance Design for Electrical Circuits: A. Ilumoka and R. Spence 87

A Methodology for Planning Experiments in Robust Product and Process Design: A. C. Shoemaker and R. N. Kacker 95

Optimization of Product and Process Design for Quality and Cost: M. S. Phadke and K. Dehnad 105

Strategies for Planning Experiments using Orthogonal Arrays and Confounding Tables: K.-L. Tsui 113

An Explanation and Critique of Taguchi's Contributions to Quality Engineering: G. Box, S. Bisgaard and C. Fung 123

Signal-to-noise Ratio Development for Quality Engineering: K. C. Kapur and G. Chen 133

Better than Taguchi Orthogonal Tables: D. Shainin and P. Shainin 143

Use of 2^{k-p} Designs in Parameter Design: J. Song and J. Lawson 151

Characterizing and Optimizing Multi-response Processes by the Taguchi Method: N. Logothetis and A. Haigh 159

Application of Taguchi Methods to Surface Mount Processes: G. R. Bandurek, J. Disney and A. Bendell 171

Worst Case Product Performance Verification with Electromagnetic Interference Test Applications: F. W. Breyfogle and J. H. Davis 183

SHORT COMMUNICATION

Estimating the Error of an Effect in Unreplicated 2-Level Fractional Factorial Designs: W. Wang and J. Lawson 189

Annotated Bibliography of Books on Experimental Design: G. J. Hahn 193

BOOK REVIEWS 198

NEWS DIGEST 200

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 202

Issue No. 3, July–September 1988

Editorial 207

SHORT COMMUNICATION
Environmental Stressing for Quality and Reliability Engineers: W. Tustin 209

The Effect of Pretinning on the Strength of a Chip Carrier Solder Joint: S. Ohlsson 215

Load-strength Simulation of Plastic Mouldings: V. Loll 223

Reliability Prediction: a Constructive Critique of MIL-HDBK-217E: H. S. Blanks 227

Interval Reliability of Spare Part Stocks: I. Bazovsky and G. Benz 235

Death by a Thousand Cuts: the Physics of Device Failure through a Series of Activated, Microscopic Events: A. J. Holden, R. W. Allen, K. Beasley and D. R. Parker 247

Subsurface Burnout Mechanisms in Gallium Arsenide (GaAs) Electronic Devices: W. R. Anderson, D. V. Morgan, F. A. Buot and A. Christou 255

Reliability and Failure Patterns Arising from Fatigue: A. D. S. Carter 269

The Bathtub does not Hold Water any More: K. L. Wong 279

NEWS DIGEST 283

Call for Papers 287

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 288

Courses in Quality and Reliability 291

BOOK REVIEWS 294

Report Review 298

Issue No. 4, October–December 1988

Editorial 299

Letter to the Editor 300

A Study of the Quality Management Methods Employed by U.K. Automotive Suppliers: D. M. Lascelles and B. G. Dale 301

Designing a Software Reliability Programme: T. C. Genadis 311

A Two-step Methodology for CMOS VLSI Reliability Improvement: Step One: M. S. Davies, R. E. Miles and V. Postoyalko 317

Detecting Lack of Control in a New, Untried Process: I. Murray and J. S. Oakland 331

Proper Subgroup Size for Statistical Process Control: D. S. Holmes and A. E. Mergen 339

Reliability Assessment of Dispenser-Type Thermionic Cathodes: J. L. Stevenson, S. M. Aagesen, R. Lotthammer and G. Kornfeld 347

NEWS DIGEST 367

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 370

BOOK REVIEWS 373

Author Index 375

Key Word Index 375

VOLUME 5, ISSUE Nos 1–4

Issue No. 1, January–March 1989

Editorial 1

Letter to the Editor 2

SHORT COMMUNICATION
An Observation on Taguchi Methods: W. A. Ganter 3

The Application of Statistical Process Control in U.K. Automotive Manufacture: Some Research Findings: B. G. Dale and P. Shaw 5

A Quality Growth Model and its Application to Initial Production Process Control: S. Yamada 17

Reliability-enabled Changes in the Design and Manufacture of Commercial Electronic Products: W. A. Ganter 23

The Roller-coaster Curve Is In: K. L. Wong 29

Reliability Problems in State-of-the-art GaAs Devices and Circuits: A. Christou 37

A Multi-failure Additive Dependability Model for Transit System Effectiveness Analysis: M. Rapone, R. Calabria and G. Pulcini 47

Reliability of Plastic-encapsulated Logic Circuits: C. Olsson 53

Logistics Support Analysis or Computer-aided Gold Digging: P.-O. Johansson and O. Wååk 73

NEWS DIGEST 81

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 84

Courses in Quality and Reliability 87

BOOK REVIEWS 89

Issue No. 2, April–June 1989

Editorial 93

Safety First — Profits Last?: B. Butler 95

Some Supplier Quality Assurance Assessment Issues: A. J. Singer, G. F. Churchill and B. G. Dale 101

Graphical and Computer-aided Approaches to Plan Experiments: A. M. Joglekar and R. N. Kacker 113

A Practical Assessment of Current Plastic Encapsulated Microelectronic Devices: J. Hughes 125

Risk Assessment and Optimization of a Safety System using the MAROS Simulation Package: I. J. A. Jardine and D. Jackson 131

Testing Control Chart Subgroups for Rationality: D. S. Holmes and A. E. Mergen 143

Failure Estimates with Replacement/Repair: S. C. Singhal and S. J. Amster 149

Reliability Predictions for Integrated Circuits from Test Structure Data: W. G. Kleppmann ... 155

The Role of SPC in Printed Circuit Board Manufacture: M. M. Manson and B. G. Dale 165

NEWS DIGEST 175

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 178

BOOK REVIEWS 181

Report Review 184

CALL FOR PAPERS 185

Issue No. 3, July–September 1989

Special Issue on Mechanical Reliability
Guest Editor: A. D. S. Carter

Editorial 187

The Failure Characteristics of Mechanical Equipment which Receives Comprehensive Maintenance Overhaul: R. F. De La Mare 189

Fault Diagnosis as an Aid to Process Machine Reliability: J. D. Summers-Smith 203

Proportional Hazards Analysis of Diesel Engine Failure Data: A. K. S. Jardine, P. Ralston, N. Reid and J. Stafford 207

Load–Strength Simulation of a Mechanical Design: V. Loll 217

The Efficient Maintenance of Offshore Structural Integrity using Reliability Analysis: J. C. P. Kam 221

Proportional Hazards Modelling of Aircraft Cargo Door Complaints: A. L. F. Leitao and D. W. Newton 229

NEWS DIGEST 239

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 244

Courses in Quality and Reliability 247

BOOK REVIEWS 249

Report Reviews 253

Issue No. 4, October–December 1989

Editorial 255

An Iterative Approach for Estimating Component Reliability from Masked System Life Data: J. S. Usher and F. M. Guess 257

User Control of Electronic Component Reliability in Spacecraft Applications: H. C. Gorton 263

Fuzzy Logic Approach to IC Quality Assurance Plan Selection: H. J. Kohoutek 267

A Computer System for the Analysis of Integrated Circuit Reliability: P. Mauri 273

Fault Detection Using Parameter Estimation: A. Pouliezos, G. Stavrakakis and C. Lefas 283

Reliability Approach for Vehicle Safety Components: F. J. Brunner 291

Imaging of Packaging-related Problems in Electronic Components by Scanning Acoustic Microscopy: K. J. Wilson, R. R. Sutherland, I. D. E. Videlo and B. Wakefield 299

A Time-series Approach to Discrete Real-time Process Quality Control: S. A. Yourstone and D. C. Montgomery 309

A Review of Reliability Evaluation Techniques Applied to InGaAs PIN Photodiodes, Germanium APDs and InGaAs APDs: J. C. D. Stokoe, P. A. Putland and R. R. Sutherland 319

NEWS DIGEST 331

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 336

BOOK REVIEWS 339

Author Index 341

Key Word Index 341

VOLUME 6, ISSUE Nos 1–5

Issue No. 1, January–March 1990

Editorial 1
Message from the Editor 3
Letter to the Editor 5
Some Problems Encountered in the Construction and Interpretation of Control Charts: B. G. Dale and P. Shaw 7
A Theoretical Approach to a Transformer Reliability Problem: J. R. Pollock and P. W. Hale. 13
Measuring Process Capability Using Indices—Some New Considerations: L. J. Porter and J. S. Oakland 19
Metal–GaAs Interaction and Contact Degradation in Microwave MESFETs: E. Zanoni, A. Callegari, C. Canali, F. Fantini, H. L. Hartnagel, F. Magistrali, A. Paccagnella and M. Vanzi 29
DoD Microcircuit Qualification Innovation—QML: E. B. Hakim 47
Analysis of a Memory Module Failure Pattern: P. W. Hale and I. K. MacTaggart 51
NEWS DIGEST 61
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 64
Courses in Quality and Reliability 67
BOOK REVIEWS 69
Report Review 70

Issue No. 2, April–May 1990

Editorial 71
Reliability Critical Thermal Model for Double-drift IMPATT Diodes on Diamond Heat Sinks: G. Csanky 73
Relay Failure Prevention by Internal Visual Inspection: J. Mejerovich and M. Brenman 85
Accelerated Life-test Experiments on Low-power Rectifier Diodes: J. Windel 93
The Dynamic Histogram Chart: D. S. Holmes and A. E. Mergen 107
The Design of Mechanical Equipment for the Limitation of In-service Failure: P. Martin 113
The Use of Taguchi Methods in Performance Demonstrations: G. R. Bandurek, H. L. Hughes and D. Crouch 121
Variation of Defect Density and its Influence on Yield Extrapolation for Integrated Circuits: W. G. Kleppmann and R.-P. Vollertsen 133
Improved Alignment of Fibre-optics Active Devices via Response Surface Methodology: E. Tan and T. N. Goh 145
NEWS DIGEST 153
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 156
BOOK REVIEWS 160
Report Reviews 162

Issue No. 3, June–August 1990

Editorial 165

Mapping Quality Assurance Systems: a Methodology: R. T. Crossfield and B. G. Dale 167

Failure Mode and Effects Analysis in the U.K. Motor Industry: a State-of-the-art study: B. G. Dale and P. Shaw 179

An Analysis of the Field Failure of Passive and Active Components: D. S. Campbell and J. A. Hayes 189

A Perspective on Shainin's Approach to Experimental Design for Quality Improvement: N. Logothetis 195

An Alternative to the Analysis of Variance for Reliability Data: R. L. Edgeman 203

System Reliability Prediction Based on Historical Data: J. S. Usher, S. M. Alexander and J. D. Thompson 209

NEWS DIGEST 219

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 224

Courses in Quality and Reliability 228

BOOK REVIEWS 230

Video Course Review 231

Issue No. 4, September–October 1990

Special Issue on Reshaping the Reliability Technology
Guest Editor: Kam L. Wong

About this Special Issue 233

Editorial 235

Letter to the Editor 236

CONCEPTS/PARADIGM

Constant Failure Rate—A Paradigm in Transition?: J. A. McLinn 237

RELIABILITY PREDICTION METHODS

How Failure Prediction Methodology Affects Electronic Equipment Design: C. T. Leonard and M. Pecht 243

What is Wrong with the Existing Reliability Prediction Methods?: K. L. Wong 251

RELIABILITY MODELLING

Arrhenius and the Temperature Dependence of Non-constant Failure Rate: H. S. Blanks 259

The Reliability Physics Approach to Failure Prediction Modelling: M. Pecht, A. Dasgupta, D. Baker and C. T. Leonard 267

Temperature Dependence of Microelectronic Device Failures: M. Pecht, P. Lall and S. J. Whelan 275

NEW FAILURE CONCERNS

Increasing Importance of Effects of Marginal Parts on Reliability: W. A. Ganter 285

RELIABILITY ASSURANCE

New Standards for Old: K. Beasley 289

RELIABILITY DEMONSTRATION

A Better Method for Verifying Production Reliability: A. Coppola 295

NEWS DIGEST 301
CALL FOR PAPERS 303
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 304
BOOK REVIEWS 308
Report Reviews 309

Issue No. 5, November–December 1990

Editorial 311
Letters to the Editor 312
Temperature–Humidity Induced Mechanisms in Plastic Encapsulated Bipolar Transistors: G. Matthäi 317
Quality Assurance of Welds in Ship Structures: G. S. Stavrakakis 323
Estimation of the Mean Cumulative Number of Failures in a Repairable System with Mixed Exponential Component Lifetimes: C. K. Hansen and P. Thyregod 329
A New Stochastic Model for Crack Propagation: H. Schäbe 341
Infant Mortality Modelling for VLSI Devices Using Graphical Estimation: P. L. Stoltze 345
The Balance Chart: A New SPC Concept: D. E. Thomas 357
NEWS DIGEST 373
CALLS FOR PAPERS 377
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 380
Courses in Quality and Reliability 383
BOOK REVIEWS 386
Author Index 389
Key Word Index 389

VOLUME 7, ISSUE Nos 1–6

Issue No. 1, January–February 1991

Editorial 1
Letters to the Editor 2
SHORT COMMUNICATION
Mean Time to System Recovery: F. M. Guess and J. Kitchin 5
Using Proportional Hazard Modelling in Plant Maintenance: C. E. Love and R. Guo 7
The Use of Expert Systems in Total Quality Management: An Exploratory Study: R. T. Crossfield and B. G. Dale 19
A Study of BS.5750 Aspirations in Small Companies: A. A. Long, B. G. Dale and A. Younger 27
Sample Size Determination of Bogey Tests Without Failures: C. J. Wang 35
On Parameter Design Optimization Procedures: B.-J. Yum and S.-W. Ko 39
NEWS DIGEST 47
CALL FOR PAPERS 52
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 54
BOOK REVIEWS 58

Issue No. 2, March–April 1991

Editorial 61

Micro and Macro Analysis of a Thermonuclear Fusion Plant for Reliability and Performance: K. Chaharbaghi and R. Buende 63

Fault Curves—A Novel Drift-fault Diagnosing Method for Condition Monitoring: P. R. Drake and J. H. Williams 89

New Methods for Specification and Determination of Component Reliability Characteristics: J. Møltoft 99

NEWS DIGEST 107

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 112

Courses in Quality and Reliability 115

Call for Papers 118

BOOK REVIEWS 119

Issue No. 3, May–June 1991

Editorial 121

Process Monitoring in Real Time: Empirical Bayes Approach—Discrete Case: M. A. Yousry, G. W. Sturm, C. J. Feltz and R. Noorossana 123

Detection of Process Upsets—Sample Autocorrelation Control Chart and Group Autocorrelation Control Chart Applications: S. A. Yourstone and D. C. Montgomery 133

The Use of Computer-aided Engineering in Reliability Studies: G. Watts 141

Application of Weibull Proportional Hazards Modelling to Bad-As-Old Failure Data: C. E. Love and R. Guo 149

An Empirical Bayes Strategy for Analysing Manufacturing Data in Real Time: G. W. Sturm, C. J. Feltz and M. A. Yousry 159

Recent Humidity Accelerations, a Base For Testing Standards: Ö. Hallberg and D. S. Peck .. 169

A Case Study on the Benefits of Combining Reliability Stress Tests: J. D. Seager and C. D. Fieselman 181

NEWS DIGEST 189

CALLS FOR PAPERS 193

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 196

BOOK REVIEWS 200

Report Reviews 201

Issue No. 4, July–August 1991

Special Issue on Electron Device Reliability Physics
Guest Editor: Emiliano Pollino

Foreword 203

Letter to the Editor 205

Modern Reliability Assurance of Integrated Circuits—A Strategy Based on Technology Capability Assessment and Production Reproducibility Control: W. Gerling 207

Microelectronic Reliability/Temperature Independence: E. B. Hakim 215

Evolution of VLSI Reliability Engineering: D. L. Crook 221

Optoelectronics Reliability: T. Ikegami and M. Fukuda 235

Electron Beam Testing: E. Wolfgang, S. Görlich and J. Kölzer 243

Failure Analysis Using Ferroelectric Liquid Crystals: B. Picart, A. Arranz, G. Oustry and B. Tromeur 249

Photon Emission as a Tool for ESD Failure Localization and as a Technique for Studying ESD Phenomena: M. Hannemann and A. Amerasekera 255

A SOM Study of DC-PBH Laser Catastrophic Failures: P. Montangero, M. Liberatore and G. Arman 261

Reliability Improvement of Electronic Circuits Based on Physical Failure Mechanisms in Components: A. C. Brombacher, H. A. De Boer, M. Bennion, P. H. Fennema and O. E. Herrmann 267

The Al–1 Per Cent Si/TiN/Ti Interconnection Scheme: Electromigration and Reliability Extrapolations: C. Caprile, G. Specchiulli, D. Sala and F. Fantini 275

Evaluation of TiW + Al/Cu Electromigration Performance: N. P. Armstrong 281

The Effect of Barrier Layers on the Distribution Function of Interconnect Electromigration Failures: M. Pinto 287

Evaluation of E^2PROM Data Retention by Field Acceleration: M. Lanzoni, R. Menozzi, C. Riva, P. Olivo and B. Ricco 293

Bimodal Lifetime Distributions of Dielectrics for Integrated Circuits: K. v. Sichart and R.-P. Vollertsen 299

Hot Carrier Degradation in MOSFETs in the Temperature Range of 77–300 K: H. E. Maes, P. Heremans, R. Bellens and G. Groeseneken 307

Reliability and Failure Analysis of GaAs MESFETs on GaAs and Si Substrates: N. Kornilios, K. Tsagaraki, J. Stoemenos and A. Christou 323

The Long-Term Stability of *n*-AlGaAs/InGaAs/GaAs Pseudomorphic HEMTs: N. L. Saunders, A. A. Rezazadeh, D. V. Morgan, H. Thomas and L. G. Hipwood 331

Degradation of Ion Implanted GaAs MESFETs: J. Goostray, H. Thomas, D. V. Morgan, R. Conlon, J. M. Dumas and G. M. Gauneau 339

Degradation Mechanisms in 2 W MESFETs: C. Canali, F. Magistrali, A. Paccagnella, M. Sangalli, C. Tedesco and E. Zanoni 343

NEWS DIGEST 351

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 354

Courses in Quality and Reliability 357

BOOK REVIEWS 359

Issue No. 5, September–October 1991

Editorial 361

Letters to the Editor 362

SHORT COMMUNICATION

Comments on 'Constant Failure Rate—a Paradigm in Transition?' by James A. McLinn: H. Ascher 363

Humidity Acceleration Factor for Plastic Packaged Electronic Devices: D. J. Klinger 365

The Role of Quality Engineering in the 1990s: D. R. Jones 371

Methods for the Continuous Assessment of Reliability of Specialized Equipment: A. J. Watkins and D. J. Leech 377

Proportional Hazards Modelling Versus Two-sample Tests: a Case Study: G. A. Bohoris and A. L. F. Leitao 393

Applying a Physics-of-failure Model to Predicting Surface Mount Solder Joint Reliability: D. E. Helling and B. Wong 403

Measuring the Quality of Knowledge Work: A. Coppola 411

Off-line Quality Control via Yield Constrained Variability Minimization in Circuit Design: A. A. Ilumoka 417

NEWS DIGEST 425

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 428

BOOK REVIEWS 431

CALL FOR PAPERS 435

Issue No. 6, November–December 1991

Process Capability Indices—an Overview of Theory and Practice: L. J. Porter and J. S. Oakland 437

Analysis of Quality Costs for Identifying Areas of Quality Improvement—a Case Study: B. Bhadury and M. K. Jain 449

Reliability of Multi-channel $Ga_{1-x}Al_xAs$ High Electron Mobility Transistor (HEMT) Integrated Circuits: A. Christou and W. Tseng 461

Transition from Quality Circles to Total Involvement in Semiconductor Manufacturing: C. A. Derry 469

Choosing the Best Set of Quality Judges: a New Quality Tool: L. L. Hoffman 475

Statistical Monitoring and Control of a Low Defect Process: T. N. Goh 479

Good Quality at Low Cost: Trends in Quality Assurance: W. Fleischhammer 485

The Physical Basis for the Roller-coaster Hazard Rate Curve for Electronics: K. L. Wong 489

Quantitative Safety Assessment of the Ventilation Recirculation System in an Undersea Mine: J. Andrews 497

NEWS DIGEST 511

CALL FOR PAPERS 515

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 516

Courses in Quality and Reliability 518

BOOK REVIEWS 520

Report Review 521

Author Index 522

Key Word Index 522

VOLUME 8, ISSUE Nos 1–6

Issue No. 1, January–February 1992

Editorial 1

Analysis of Reliability of Powder Metallurgy Steels by Means of Weibull Statistics: G. Straffelini and A. Molinari 3

TEMPEX: an Expert System for Temperature Control in an Injection Moulding Process: E. Oztemel and D. T. Pham 9

Cumulative Score Charts: G. Box and J. Ramirez 17

A Two-stage Sampling Plan for Bogey Tests: C. Wang and M.-W. Lu 29

Investigation and Characterization of a Control Scheme for Multivariate Quality Control: M.-K. Chua and D. C. Montgomery 37

The Use of a Generalized Signal-to-noise Ratio to Identify Adjustment and Dispersion Factors in Taguchi Experiments: A. Winterbottom 45

Convenient Construction of *t*-tests for Quality Evaluation: J. A. Nachlas 57

Practical Alternatives for Estimating the Failure Probabilities of Censored Life Data: G. S. Wasserman and I. S. Reddy 61

NEWS DIGEST 69

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 72

BOOK REVIEWS 75

Issue No. 2, March–April 1992

Editorial 77

Fault and Cause Diagnosis of Casting Defects: a Case Study: F. Б. J. Sweeting, W. R. Thorpe and A. N. Pettitt 79

Low-cost Physical Analysis Techniques for the Failure Analysis of Semiconductor Components: J. Y. Glacet and G. Guerri Dall'oro 93

Failures in Thin Metal Film Resistors—a Case History: J. F. Cain, L. Hart and J. R. McLean . 99

On the Effectiveness of the Unit Sample Size for Standard Control Charts: ARL vs. AURAL: J. M. Snow, J. S. Usher and B. E. Stuckman 105

Control Chart Design: a Review of Standard Practice: L. J. Porter and R. Caulcutt 113

Testing for Reliability Improvement or Deterioration in Repairable Systems: R. F. De La Mare 123

Statistical Analysis of an Age Model for Imperfectly Repaired Systems: R. Guo and C. E. Love 133

NEWS DIGEST 147

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 150

Courses in Quality and Reliability 154

BOOK REVIEWS 156

Issue No. 3, May–June 1992

Special Issue on Quality and Reliability of Electronic Devices
Guest Editor: André Touboul

Editor's Comments: A. Touboul 159

RELIABILITY AND CASE STUDIES

Reliability Behaviour of Electronic Components as a Function of Time: D. S. Campbell, J. A. Hayes, J. A. Jones and A. P. Schwarzenberger 161

The Influence of Temperature on Integrated Circuit Failure Mechanisms: M. Pecht, P. Lall and E. B. Hakim 167

Floating Gate Memories Reliability: G. Crisenza, C. Clementi, G. Ghidini and M. Tosi 177

Environmental Testing and Component Reliability Observations of Telecommunications Equipment Operated in Tropical Climatic Conditions: N. Sinnadurai, T. S. Kuppuswamy, R. Chandramouli and B. K. N. Rao 189

Plastic Encapsulated ICs in Military Equipment Reliability Prediction Modelling: M. Brizoux, G. Deleuze, R. Digout and M. Nallino 195

TEST STRATEGY

ASICs Failure Analysis Using Two Complementary Techniques: External Electrical Testing and Internal Contactless Laser Beam Testing: C. Bouvet, P. Fouillat, J. P. Dom and Y. Danto 213

Use of a CMOS Static Memory Array as a Technology Test Vehicle: D. Schmitt-Landsiedel, J. Winnerl, G. Neuendorf and J. Kölzer 219

ADVANCED ANALYSIS TECHNIQUES

Emission Microscopy: J. Kölzer, A. Dallmann, G. Deboy, J. Otto and D. Weinmann 225

Failure Analysis of Multilevel Metallized LSI Using Optical Beam Induced Current: J. Mitsuhashi, S. Komori and N. Tsubouchi 239

Ultrasonic Microscope Investigations of Die Attach Quality and Correlations with Thermal Resistance: G. Pfannschmidt 243

ELEMENTARY FAILURE MECHANISMS

An Extension of the Rapid Wafer-level WIJET Method and its Comparison with Conventional Electromigration Testing: F. Jeuland, Ph. Normandon, G. Lormand and A. Boudou 247

Electromigration at Gold–Aluminium Interfaces and in Thin Aluminium Tracks: B. Vanhecke, L. De Schepper, W. De Ceuninck, V. D'Haeger, M. D'Olieslaeger, E. Beyne, L. Stals and J. Roggen 253

ESD in Integrated Circuits: A. Amerasekera and J. Verwey 259

Transiently Triggered Latch-up in CMOS Twin-tub and Epitaxial Technologies: P. Pavan, P. Caprara, M. Stucchi and E. Zanoni 273

COMPOUND SEMICONDUCTOR DEVICES

Stability of Interfaces in Pseudomorphic InGaAs HEMTs: P. Audren, J. M. Dumas, S. Mottet, C. Vuchener, J. Paugam and M. P. Favennec 279

Reliability and Degradation of 980 nm InGaAs/GaAs Strained Quantum Well Lasers: M. Fukuda, M. Okayasu, T. Takeshita and M. Wada 283

ESD Induced Degradation Mechanisms of InGaAsP/InP Lasers: F. Magistrali, D. Sala, G. Salmini, M. Vanzi, F. Fantini, M. Giansante and L. Zazzetti 287

GaAs MMIC Reliability Studies: W. T. Anderson, J. A. Roussos and K. A. Christianson 295

Low Frequency Noise Analysis to Detect the Influence of Deep Levels in AlGaAs/GaAs HEMTs: N. Labat, D. Ouro Bodi, A. Touboul, Y. Danto and J.-M. Dumas 301

NEWS DIGEST 307

Call for Papers 311

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 312

BOOK REVIEWS 316

Report Reviews 317

Issue No. 4, July–August 1992

Editorial 319

Letters to the Editor: Standards on Quality and Reliability 320

Call for Papers 324

Component Lifetime Models Based on Weibull Mixtures and Competing Risks: C. K. Hansen and P. Thyregod 325

Reliability and Performance Analysis of Time–Space–Time Switching Networks with Multiple Separated Space Switches: D. K. Sung and S. H. Kang 335

Improved Structural Reliability Assessment using Non-linear Regression Techniques to Process Raw Fatigue Crack Growth Test Data: G. S. Stavrakakis 341

Economical Design of Reliable Systems—Some Practical Situations: K. K. Aggarwal 349

Some Procedures for Decision Making in Controlling High Yield Processes: M. Xie and T. N. Goh 355

Using Step Stress to Explore the Kinetics of Failure: M. J. LuValle and L. L. Hines 361

An Extended Mathematical Model for Failure Kinetics: A. Drapella 371

NEWS DIGEST 375

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 378

COURSES IN QUALITY AND RELIABILITY 382

BOOK REVIEWS 384

Report Review 386

Issue No. 5, September–October 1992

Special Issue on Total System Reliability
Guest Editor: Samuel J. Keene

Editorial 387

Letter to the Editor 389

What Happened to the System Perspective in Reliability?: M. Halverson and D. Ozdes 391

Applications of Hazard Rate Profile to Software Reliability Prediction, Growth Modelling and Allocation: M. A. Friedman 413

Combined Hardware and Software Aspects of Reliability: S. Keene and C. Lane 419

Assuring Quality of the Human–Computer Interface: H. J. Kohoutek 427

Using the Economic Point of Truncation Process for New Product Introduction: J. T. Zurn 441

Software Reliability Model Selection: T. M. Khoshgoftaar and T. G. Woodcock 457

System Reliability Analysis Using Factorization Techniques: M. S. Kendall, J. W. Koslov and R. B. Wood 471

Quality and Reliability Assessment of Hardware and Software during the Total Product Life Cycle: D. R. Jones, V. Murphy and J. Blanchard 477

Fault Impact and Fault Tolerance in Multiprocessor Interconnection Networks: B. Menezes, A. M. Johnson, Jr., M. Malek, R. Jenevein and K. H. Yau 485

On the Measurement of Field Return Rates: M. S. Shen 501

NEWS DIGEST 511
Call for Papers 513
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 514
BOOK REVIEWS 518
Report Review 520

Issue No. 6, November–December 1992

Editorial 521
A Structural Reliability Model for Composite Materials: A. Corvi and D. Vangi 523
Reliability and Robustness of Thin Film Composite Resistor Networks: A. Sachaf and I. E. Klein 531
A Comparison of Control Charts from the Viewpoint of Change-point Estimation: K. Nishina 537
Supply Current Monitoring in CMOS Circuits for Reliability Prediction and Test: A. M. Richardson and A. P. Dorey 543
Formal Methods: the Next Generation of System Design Tools: M. Schofield 549
Pragmatic Procedure for the Estimation of Thin Dielectric Reliability: R.-P. Vollertsen 557
NEWS DIGEST 565
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 570
Courses in Quality and Reliability 574
BOOK REVIEWS 576
Author Index 577
Kev Word Index 579

VOLUME 9, ISSUE Nos 1–6

Issue No. 1, January–February 1993

Editorial 1
Letter to the Editor 2
SHORT COMMUNICATION
BITE and Unconfirmed Failures: R. A. Rees 3
Reliability Improvement via Taguchi's Robust Design: M. Hamada 7
Fault and Cause Diagnosis of Casting Defects: Case Study No. 2: F. B. J. Sweeting, W. R. Thorpe and A. N. Pettitt 15
Quality-based Design by Probability Optimization: D. B. Parkinson 29
Optimization Strategies in Robust Engineering Design and Computer-aided Design: R. J. Buck and H. P. Wynn 39
Total Customer Satisfaction as a Business Strategy: W. B. Smith Jr 49
Using Rainbow Net Simulation to Measure Fault Tolerance in a Multiprocessor: A. M. Johnson Jr., M. A. Schoenfelder and D. J. Lebold 55
Detecting Test Set Hardware Degradation using Statistical Data Modelling: R. W. Potter and G. W. Sturm 63

NEWS DIGEST 69
Call for Papers 73
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 74
Call for Papers 78
BOOK REVIEWS 79

Issue No. 2, March–April 1993

Editorial 81
LETTER TO THE EDITOR
Special Report: Survey of the Present Status on Critical Reliability Issues within Europe: H. E. Maes 83
The Japanese Point of View on the ISO 9000 Standards: H. Kume 85
SPC of a Near Zero-defect Process Subject to Random Shocks: M. Xie and T. N. Goh 89
A Computer-controlled Environmental Test System for High Pin-count Integrated Circuit Packages: J. Barrett, J. Ó. Donavan, T. Hayes and S. C. Ó. Mathúna 95
Simple Adjustments to Improve Control Limits on Attribute Charts: A. Winterbottom 105
A Method of Identifying Latent Human Errors in Work Systems: T. Nakajo 111
The Electrical Design for Manufacture of Ceramic Capacitors: C. D. Hannaford and H. Ingleson 121
An Application of a Bathtub Failure Model to Imperfectly Repaired Systems Data: C. E. Love and R. Guo 127
Using Sneak Circuit Analysis in Aerospace Product Assurance: J. Deckers and H. Schäbe .. 137
A Comparative Reliability Assessment of 750 nm, 1060 nm and 1300 nm High Power Surface Light Emitting Diodes: C. E. Lindsay 143
NEWS DIGEST 149
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 152
Call for Papers 156
Courses in Quality and Reliability 157
BOOK REVIEWS 159

Issue No. 3, May–June 1993

Special Issue on Total Quality Management in Engineering
Guest Editor: John S. Oakland

Call for Papers ii
Editorial 161
Quality and Reliability: Illusions and Realities: P. D. T. O'Connor 163
The Key Features of Japanese Total Quality Control: B. G. Dale 169
Total Quality Management in Hong Kong Industry and its Subsidiaries in China: T. Y. Lee . 179
Taguchi Methods: Some Technical, Cultural and Pedagogical Perspectives: T. N. Goh 185
The Total Costs of Quality: What Else Should be Contemplated?: S. H. Elsen and R. F. Followell 203

A New Approach to Reliability of Commercial and Military Aerospace Products: Beyond Military Quality/Reliability Standards: G. A. Kromholtz and L. W. Condra 211

Consistency in Quality—a Baseline for Achieving Total Quality Management: M. H. Carlsson 217

NEWS DIGEST 227

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 232

BOOK REVIEWS 236

Issue No. 4, July–August 1993

Special Issue: Papers presented at the European Symposium on Reliability of Electron Devices, Failure Physics and Analysis 1992 (ESREF '92), Schwäbisch Gmünd, Germany, October 1992
Guest Editors: H. H. Berger and W. H. Gerling

Editor's Comments: H. H. Berger and W. H. Gerling 237

Simulation, a Tool for Designing-in Reliability: A. Brombacher, E. van Geest, R. Arendsen, A. Van Steenwijk and O. Herrmann 239

The Impact of Electronic Components on the Reliability of Cars: H.-G. Kumpfmüller 251

Field Components Reliability Analysis for French Telecommunications Equipment: J. Y. Boulaire, B. Bauduin and A. Lelievre 257

Plastic Encapsulated IC Reliability Prediction Modelling: Principal Results: M. Nallino, R. Digout, G. Deleuze and M. Brizoux 267

Robust Design of Circuits Susceptible to Electromigration: E. van Geest, A. Brombacher and O. Herrmann 281

Electromigration, Models and Atomistic Interpretation: R. Kirchheim 287

Electromigration Early Resistance Increase Measurements: J. Niehof, P. A. Flinn and T. J. Maloney 295

Electromigration in AlCu Interconnections with W-plug Contacts: L. Ferlazzo, G. Reimbold, J. P. Gonchond, M. Heitzmann, O. Demolliens and G. Lormand 299

Thermoreflectance Optical Test Probe for the Measurement of Current-induced Temperature Changes in Microelectronic Components: W. Claeys, S. Dilhaire, V. Quintard, J. P. Dom and Y. Danto 303

On the Use of DC Measurements for ESD-related Process Monitoring: J. M. Luchies, F. Kuper and J. Verweij 309

Analysis of ESD Protection Networks for DMOS Power Transistors by Means of Static and Time-resolved Emission Microscopy: B. Bonati, A. Canclini, M. Cavone, E. Novarini, P. Pavan, R. Rivoir, M. Stucchi and E. Zanoni 315

Breakdown Characteristics of Gate and Tunnel Oxides versus Field and Temperature: C. Monsérié, P. Mortini, G. Ghibaudo and G. Pananakakis 321

A New Approach to Statistically Modelling the Time-dependent Oxide Breakdown: R.-P. Vollertsen 325

Limitations of Oxide Breakdown Accelerated Testing for Reliability Simulation: M. Nafría, J. Suñé and X. Aymerich 333

Two-dimensional Modelling and Characterization of Gate-to-drain Overlap Contribution on the Leakage Current of a MOSFET, used as a GCD: E. Ciantar, S. Burgniard, R. Jérisian and J. Oualid 337

Reliability Issues of Offset Drain Transistors after Different Modes of Electrical Stress: C. Papadas. P. Mortini, C. Monsérié, G. Ghibaudo and G. Pananakakis 341

Reliability Simulations of the Endurance Performance of FLOTOX EEPROM Cells using SPICE: F. Gigon, C. Papadas, G. Ghibaudo, G. Pananakakis and P. Mortini 347

Analysis of MOS SOI Transistor Degradation: V. Berland, A. Touboul and O. Flament 353

Low Frequency Noise and Reliability Analysis of Avalanche Photodiodes: B. K. Jones and D. A. Kozlowski 359

Degradation Behaviour of Highly Coherent 1·55 μm Long-cavity Multiple Quantum Well DFB Lasers: M. Fukuda, F. Kano, T. Kurosaki and J.-I. Yoshida 363

Failure Mechanisms in Life-tested HEMTs: W. T. Anderson, K. A. Christianson and C. Moglestue 367

Failures of AlGaAs/GaAs HEMTs Induced by Hot Electrons: C. Tedesco, C. Canali, F. Magistrali, A. Paccagnella and E. Zanoni 371

Very High Temperature Test of InP-based Laser Diodes: M. Tesauri, G. Chiorboli, P. Cova, F. Fantini, F. Magistrali and D. Sala 377

MATHEMATICAL CORNER 383

NEWS DIGEST 387

CALL FOR PAPERS 391

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 392

Courses in Quality and Reliability 396

BOOK REVIEWS 398

Issue No. 5, September–October 1993

Editorial 399

Correlation between EMI-induced Failures and Large-signal Response of FET-input Opamps: D. Golzio, S. Graffi, Z. M. V.-Kovács and G. Masetti 401

Analysis of Run-in Process for PC Manufacturing: A. Accumolli 407

Maintenance Planning and Resource Allocation in a Urea Fertilizer Plant: D. Kumar and P. C. Pandey 411

Autoclave Tests of 64K and 256K SRAMs: H. A. Polman and K. Fokkens 425

Product Warranty and Quality Control: D. P. Murthy, R. J. Wilson and I. Djamaludin 431

A General Approach for Testing the Process Capability Index: L. L. Hoffman 445

Consideration of Maintenance Objectives in the Design and Development of Software: K. C. Keene and S. J. Keene 451

NEWS DIGEST 459

Call for Papers 463

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 464

BOOK REVIEWS 467

Report Review 468

Issue No. 6, November–December 1993

Editorial 469

On Parameter Design of Binary-input-and-binary-output Dynamic Systems: B.-J. Yum and S.-J. Kim 471

Localization and Characterization of Latch-up Sensitive Areas using a Laser Beam: Influence on Design Rules of ICs in CMOS Technology: P. Fouillat, Y. Danto and J. P. Dom 477

Reliability Testing of Polyimides for GaAs MMIC Applications: R. F. B. Conlon and J. A. Turner 483

A Comparison of Deterministic and Statistical Sampling Techniques for Quality Analysis of Integrated Circuits: A. A. Ilumoka 489

Comparative Study of Quantitative Models for Hardware, Software and Human Reliability Assessment: L. Bodsberg 501

Computer Simulation of Fast Electromigration Lifetime Determination Techniques: T. H. Gilfedder and B. K. Jones 519

NEWS DIGEST 525

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 528

Courses in Quality and Reliability 531

CALL FOR PAPERS 532

BOOK REVIEWS 533

Author Index 535

Key Word Index 537

VOLUME 10, ISSUE Nos 1–6

Issue No. 1, January–February 1994

Editorial 1

Letter to the Editor 2

Obituary 3

Maximum Likelihood Estimation from Record-breaking Data for the Weibull Distribution: L. A. Hoinkes and W. J. Padgett 5

Accelerated Ageing with *in situ* Electrical Testing: a Powerful Tool for the Building-in Approach to Quality and Reliability in Electronics: L. De Schepper, W. De Ceuninck, G. Lekens, L. Stals, B. Vanhecke, J. Roggen, E. Beyne and L. Tielemans 15

Tolerance Design: Choosing Optimal Tolerance Specifications in the Design of Machined Parts: A. Jeang 27

Simulation Strategies to Identify the Failure Parameters of Repairable Systems under the Influence of General Repair: C. E. Love and R. Guo 37

A Review of the Literature on the use of SPC in Batch Production: M. Al-Salti and A. Statham 49

Operational Life Testing of Power Transistors Switching Unclamped Inductive Loads: G. L. White 63

A Reduced Sampling Approach for Reliability Verification: C. R. Allmen and M.-W. Lu 71

NEWS DIGEST 79

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 82

BOOK REVIEWS 85
Report Reviews 86

Issue No. 2, March–April 1994

Editorial ii
Short-run Statistical Process Control: *Q*-chart Enhancements and Alternative Methods: E. Del Castillo and D. C. Montgomery 87
Numerical Differences in the Survival Probabilities obtained by the Cumulative-hazard and Kaplan–Meier Estimators of the Reliability Function: G. A. Bohoris 99
Gamma Function Tables for the Estimation of the Mean and Standard Deviation of the Weibull Distribution: G. A. Bohoris 105
Making Full Use of Taguchi's Orthogonal Arrays: D. K. J. Lin 117
Robust Design of a Polysilicon Deposition Process using Split-plot Analysis: B. S. Cantell and J. G. Ramírez 123
Reliability Engineering Concepts in Design for Usability: H. J. Kohoutek 133
Use of Off-line and On-line Controls for the Manufacture of Quality Rings for Bearings—a Case Study: A. P. John and B. Bhadury 143
MATHEMATICAL CORNER 155
NEWS DIGEST 162
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 164
Courses in Quality and Reliability 167
BOOK REVIEW 169
Report Reviews 169

Issue No. 3, May–June 1994

Editorial 171
TENTH ANNIVERSARY OF QREI
Quality and Reliability in the Future: Directions and Training 173
What's New in Reliability Engineering?: A. Coppola 175
Quality and Reliability Research into the Next Century: H. S. Blanks 179
Teaching Quality and Reliability Engineering: R. I. Grosvenor, H. Rowlands and J. H. Williams 185
Quality and Reliability Engineering in Higher Education: W. G. Black 189
Quality in Education—ISO9000 as a Tool?: J. Osborne 191
Quality in Engineering Education?: K. Budree 193
Hardware Reliability Assurance and Field Experience in a Telecom Environment: Ö. Hallberg, B. Eriksson, R. Francis, R. Hjortendal, L. I. Lindberg and B. Sävström 195
Local-area Network Reliability Models: J. Spragins 201
'On-line' G-control Chart for Attribute Data: L. A. Glushkovsky 217
A Stochastic Approach to Consequence Tree Analysis: H. Schäbe 229

Testing of the Quality of Solder Joints through the Analysis of their Thermal Behaviour with an Interferometric Laser Probe: W. Claeys, V. Quintard, S. Dilhaire, D. Lewis and Y. Danto 237

NEWS DIGEST 243

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 248

BOOK REVIEWS 251

Report Review 252

Issue No. 4, July–August 1994

Special Issue: Papers presented at the European Symposium on Reliability of Electron Devices, Failure Physics and Analysis 1993 (ESREF '93), Bordeaux, France, October 1993
Guest Editors: N. Labat and A. Touboul

Editorial: N. Labat and A. Touboul 253

Integration of Efforts for the Reliability of Microelectronic Devices: W. Gerling 255

Component Lifetime Modelling: J. F. Verweij, A. C. Brombacher and M. M. Lunenborg 263

Implementation of Laser Beam Sensitive Cells: a New Approach for Integrated Circuits Testing: P. Fouillat, S. Gervais-Ducouret, H. Lapuyade and J. P. Dom 273

Testability Enhancement of a Basic Set of CMOS Cells: M. Rullán, J. Oliver, C. Ferrer and F. C. Blom 279

Early Detection of Ageing in Solder Joints through Laser Probe Thermal Analysis of the Peltier Effect: W. Claeys, V. Quintard, S. Dilhaire, D. Lewis and Y. Danto 289

Application of Defect Simulation as a Tool for more Efficient Failure Analysis: S. Griep, J. Khare, R. Lemme, U. Papenberg, D. Schmitt-Landsiedel, W. Maly, D. M. H. Walker, J. Winnerl and T. Zettler 297

Reliability Modelling for Electromigration Failure: J. R. Lloyd 303

The Use of Early Resistance and Early TCR Changes to Predict the Reliability of On-chip Interconnects: V. D'Haeger, H. Stulens, W. De Ceuninck, L. De Schepper, L. Tielemans,G. Gallopyn, P. De Pauw and L. M. Stals 309

Electrical Measurements as Performance Indicators of Electromigration: B. K. Jones, Y. Z. Xu and T. C. Denton 315

Observation of Submicronic Contacts and Vias by Scanning Ion and Electron Microscopy: R. Pantel, G. Mascarin, J. P. Gonchond and D. Lafond 319

Analysis of HBM ESD Testers and Specifications using a Fourth-order Lumped Element Model: K. Verhaege, P. J. Roussel, G. Groeseneken, H. E. Maes, H. Gieser, C. Russ, P. Egger, X. Guggenmos and F. G. Kuper 325

Compact Electro-thermal Simulation of ESD-protection Elements: C. Russ, H. Gieser, P. Egger and S. Irl 335

A CDM-only Reproducible Field Degradation and its Reliability Aspect: H. A. Gieser, P. Egger, J. C. Reiner and M. R. Herrmann 341

Correlation between $1/f$ Noise and Semiconductor Laser Degradation: M. Fukuda, T. Hirono, T. Kurosaki and F. Kano 351

MATHEMATICAL CORNER 355

NEWS DIGEST 359

INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 362

Courses in Quality and Reliability 365

BOOK REVIEWS 367

Issue No. 5, September–October 1994

Special Issue on Testing in Engineering
Guest Editor: Valter Loll

Editor's Comments: V. Loll 369
Product Certification and Standards for Testing: V. Loll 371
Knowledge-based Qualification Tests for Electronic Components in Harsh Environments: J. M. Hu 377
Practical Reliability Testing Considerations: S. J. Keene and P. Vattano 391
Reliability Engineering Based on Field Information—the Way Ahead: J. Møltoft 399
Best Compromise Test Plans for Weibull Distribution with Different Censoring Times: G. Yang and L. Jin 411
Taguchi Methods in Practice: an Analysis of Goh's Paradox: T. N. Goh 417
Testing of a Solder Replacement Technology: H. L. Hvims 423
APPLICATION NOTES
A Practical Example for Reduction of the Call Rate Level: P. Rimmen 435
Weibull Analysis of Fatigue Test Data: K.-E. Olsson 437
NEWS DIGEST 439
ERRATUM 445
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 446
BOOK REVIEW 450

Issue No. 6, November–December 1994

Editorial 451
Letter to the Editor 453
Benchmarking Barometers for Products and Processes: H. A. Malec 455
Real-time Empirical Bayes Manufacturing Process Monitoring for Censored Data: C. J. Feltz and G. W. Sturm 467
A Comparison of Mean and Range Charts with Pre-control Having Particular Reference to Short-run Production: P. F. Tang and N. Barnett 477
NEWS DIGEST 487
CALLS FOR PAPERS 488
INTERNATIONAL CALENDAR OF FORTHCOMING EVENTS 490
Courses in Quality and Reliability 493
BOOK REVIEWS 494
Report Review 495
Author Index 497
Key Word Index 499